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Date: August 27, 2001

Sonia Molegn

#1/a Hawkins 9/6/01

PATENT 36856.345

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Masaya WAJIMA et al.

Serial No.: 09/656,106

Filed: September 6, 2000

Title: CHIP ELECTRONIC COMPONENT

AND MOUNTING STRUCTURE OF THE

SAME

Art Unit: 2834

Examiner: J. Gonzalez

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AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Office Action dated April 27, 2001, the period for response to which has been extended by the enclosed Petition For One Month Extension of Time, please reconsider the above-identified patent application for the reasons set forth in the following paragraphs.

IN THE SPECIFICATION:

Please replace the first full paragraph on page 19 with the following paragraph:

Therefore, as in the chip electronic component 1 of the first preferred embodiment, the external electrodes 18 to 20 have narrow portions and wide portions respectively, formation of solder fillets is prevented and thereby the mounting density is

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